

**METHOD AND APPARATUS FOR IMPLEMENTING SILICON WAFER
CHIP CARRIER PASSIVE DEVICES**

Abstract of the Disclosure

5 Methods and apparatus are provided for implementing silicon wafer
chip carrier passive devices including customized silicon capacitors and
resistors mounted directly on a module or carrier package. A plurality of
system design inputs is received for a package arrangement. A respective
physical design is generated for customized passive devices, a logic chip,
and a chip carrier. Silicon devices are fabricated utilizing the generated
10 respective physical design for customized passive devices and the logic chip
and a carrier package is fabricated. The fabricated silicon devices are
assembled on the carrier package.